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(54) **POWER SUPPLY DEVICE HAVING THERMAL INSULATION FUNCTION**

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(57) **ABSTRACT**

A power supply device having a thermal insulation function includes a circuit board, and at least one heat-sensitive component and a plurality of heat-generating electronic components that are disposed on the circuit board and spaced apart from one another. The heat-generating electronic components include a transformer, an inductor, an integrated circuit, or a metal oxide semiconductor (MOS). A minimum distance between the heat-sensitive component and the heat-generating electronic components is 7 mm. A thermal insulation area is defined between the heat-sensitive component and the heat-generating electronic components, and none of the heat-generating electronic components is disposed within a 270° range of the thermal insulation area. The heat-generating electronic components are disposed outside the thermal insulation area to separate the heat-sensitive component from a heat source on the circuit board, such that a high temperature of the heat source has less influence on the heat-sensitive component.